TAI-SAW TECHNOLOGY CO., LTD.

No. 3, Industrial 2nd Rd., Ping-Chen Industrial District,
Taoyuan, 324, Taiwan, R.O.C.
TEL: 886-3-4690038 FAX: 886-3-4697532
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Product Specifications Approval Sheet

Product Description: Dielectric Filter3700MHz BW 200MHz Size 15.9x6.2mm
TST Parts No.: TR0121AA0090

Customer Parts No.:_____

Customer signature required

Company:_____

Division:_____

Approved by :_____

Date:_____

Checked by:_____ Nina Chen Nina Chen

Approved by:_____ Kazuma Lee Kazuma Lee

Date:_____ 2023/04/17

1. Customer signed back is required before TST can proceed with sample build and receive orders.
2. Orders received without customer signed back will be regarded as agreement on the specifications.
3. Any specifications changes must be approved upon by both parties and a new revision of specifications shall be released to reflect the changes.

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Dielectric Filter 3700MHz BW 200MHz Size 15.9x6.2mm

MODEL NO.: TR0121AA0090 REV. NO.:1.0

A. Maximum Rating:

1. Input Power:1W
2. Operating Temperature: -40°C to +85°C
3. Storage Temperature: 0°C to +40°C
4. Moisture Sensitivity Level: 2a(MSL 2a)

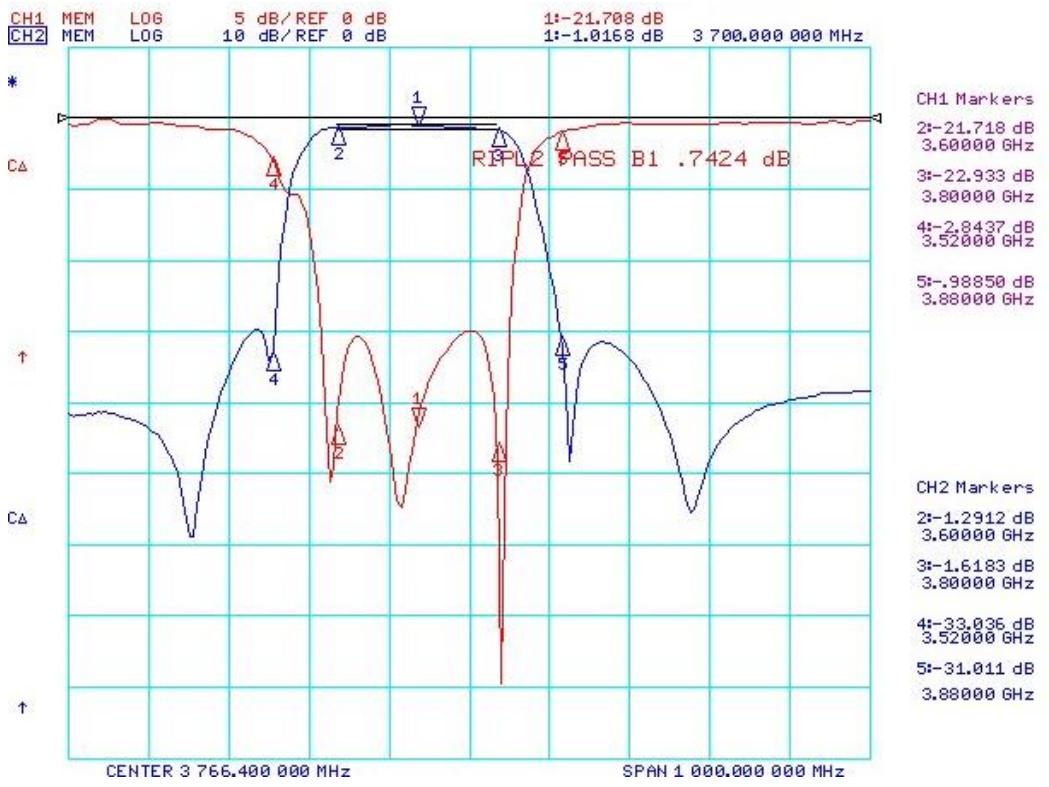
RoHS Compliant
Lead free
Lead-free soldering

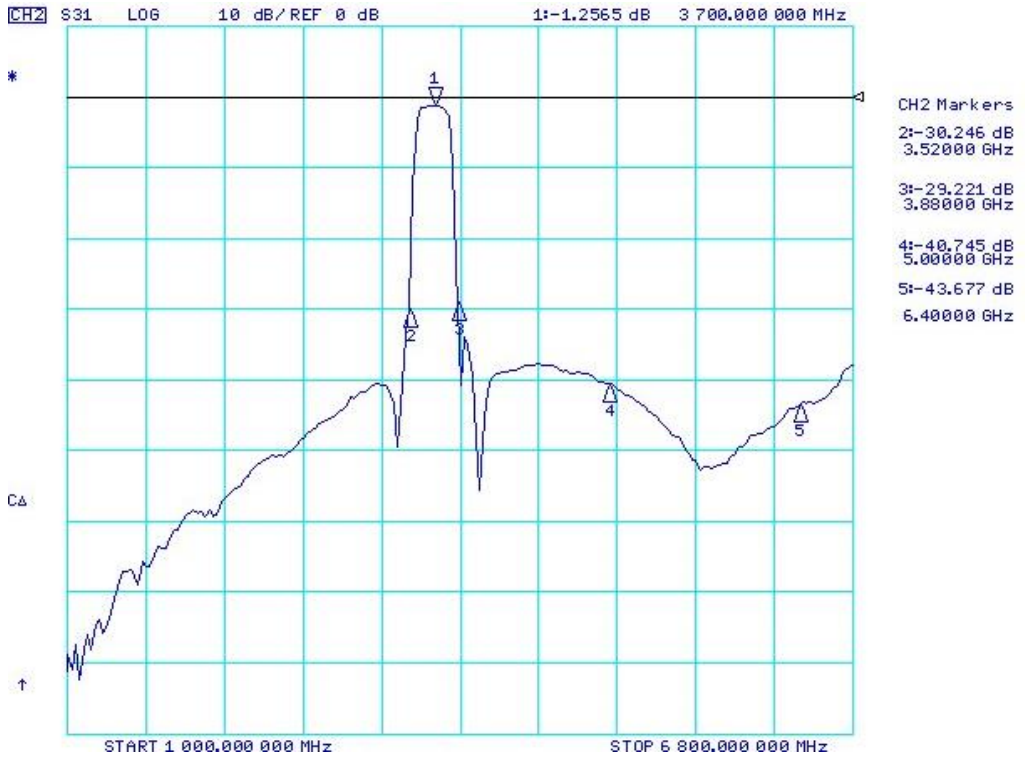
Electrostatic Sensitive Device (ESD)

B. Electrical Characteristics:

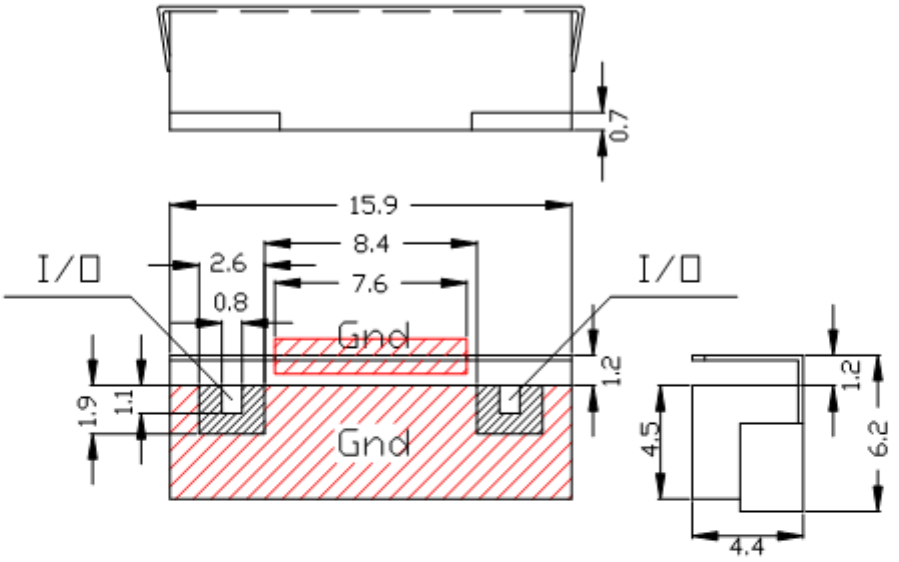
ITEM		SPECIFICATION		
		Min	Typ	Max
INSERTION LOSS	3600~3800 MHz		1.8 dB	2.0 dB
RIPPLE	3600~3800 MHz		0.7 dB	1.0 dB
RETURN LOSS	3600~3800 MHz	10 dB	13 dB	
ATTENUATION	at 3520 MHz	25 dB		
	at 3880MHz	25 dB		
ATTENUATION specifies the absolute value of attenuation.				

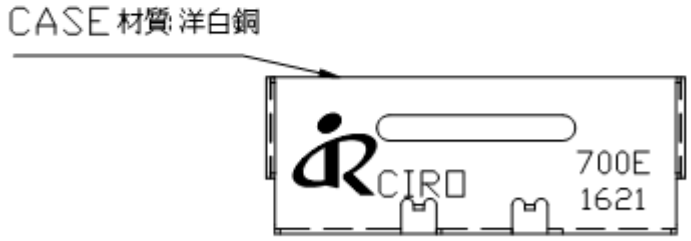
C. Frequency Characteristics:





D. Dimension:



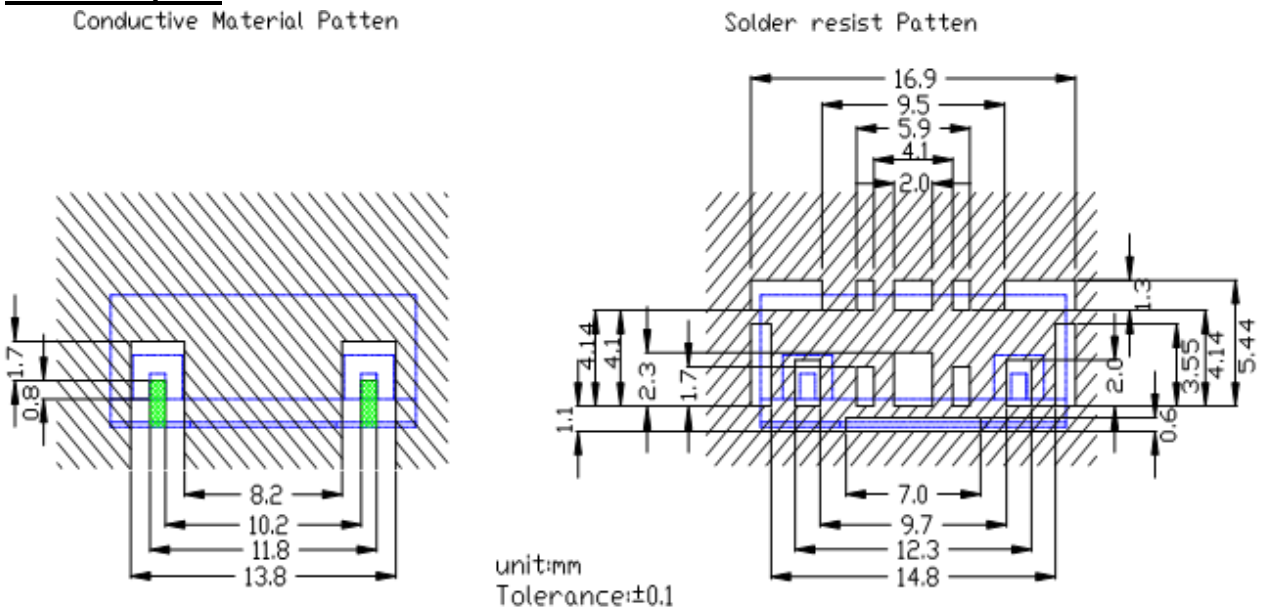


I/O: Input / Output
Gnd:Ground

700E: product name
1621: year/week (2016 21th week)
Color: Black

Unit:mm
Tolerance:±0.3

E. PCB Footprint:



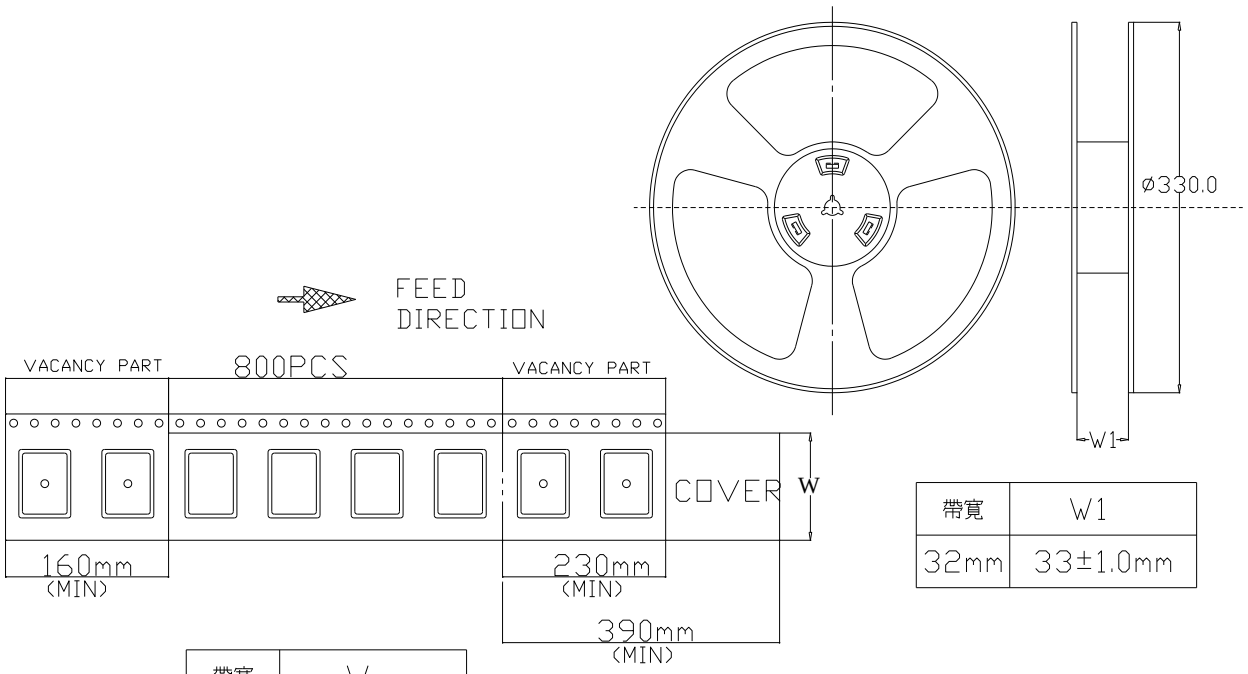
Conductive Material: Ground,connected to lower geound diameter of 0.3mm and max.distance of3.0mm.

covered with solder resist.

I/O Pads must be connected to lineswith 50Ω impedance. in the application a termination of 50Ω must be realized.

F.Packing:

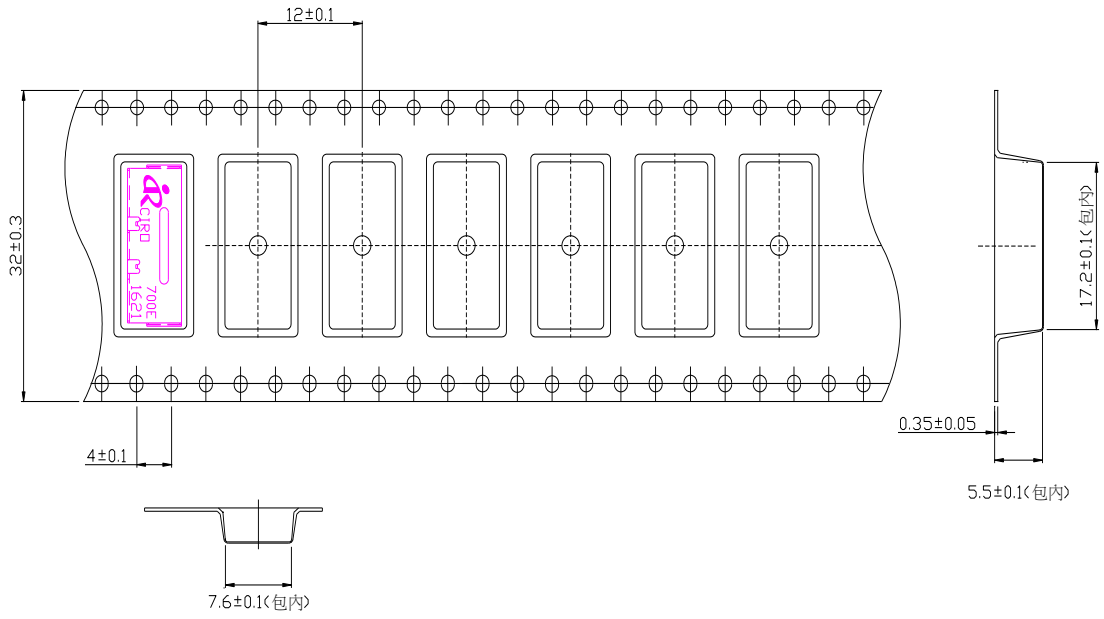
1.Reel Dimension:



帶寬	W
32mm	25.5±0.1mm

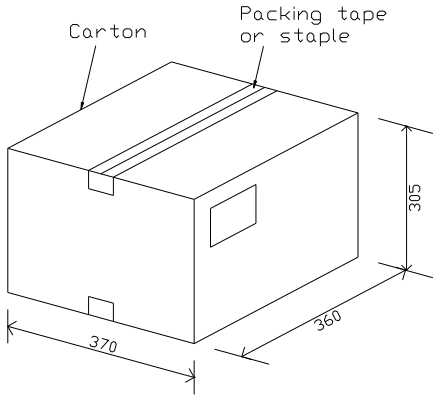
帶寬	W1
32mm	33±1.0mm

2.Tape Dimension:

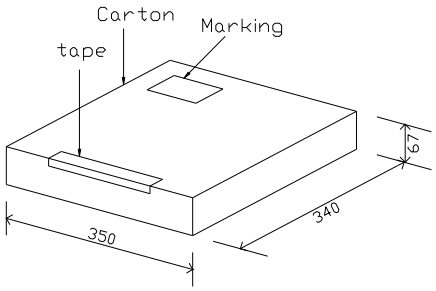


3.Package style:

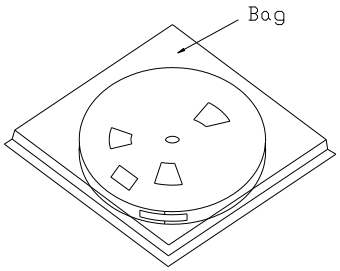
1. Outer Carton
   Quanyity:3200PCS



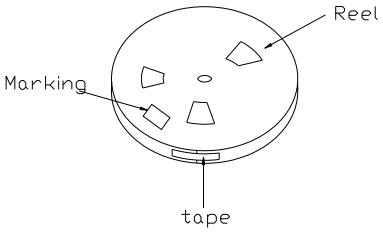
2. Inner Carton
   Quanyity:800PCS



3. Bag
   Quanyity:800PCS



4. Taping
   Quanyity:800PCS



Unit:mm

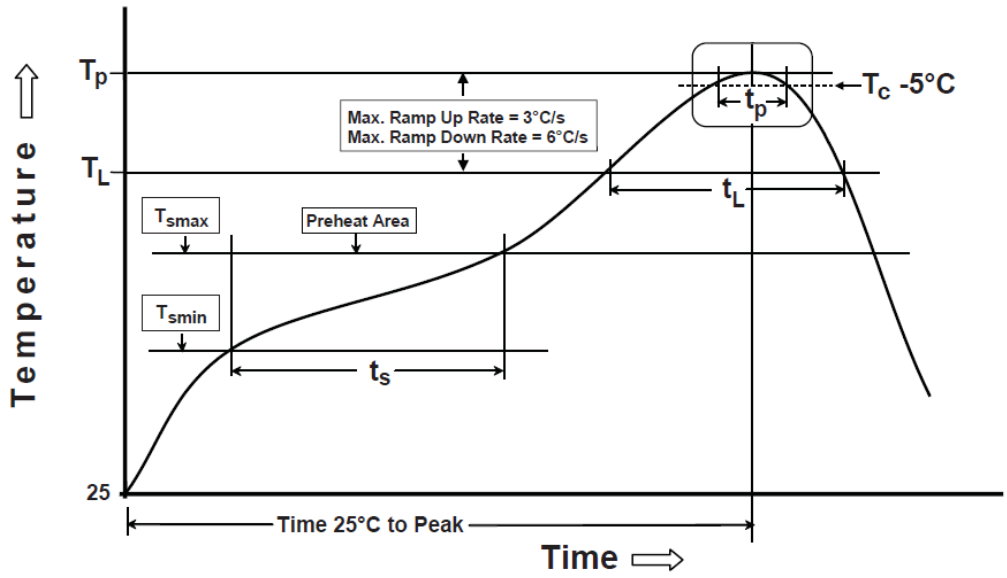
G. Recommended Reflow Profile:

Products can be assembled following Pb-free assembly. According to the Standard **IPC/JEDEC J-STD-020C**, the temperature profile suggested is as follow:

Phase	Profile features	Pb-Free Assembly (SnAgCu)
PREHEAT	-Temperature Min(Tsmin) -Temperature Max(Tsmax) -Time(ts) form (Tsmin to Tsmax)	150℃ 200℃ 60-120 seconds
RAMP-UP	Avg. Ramp-up Rate (Tsmax to TP)	3℃/second(max)
REFLOW	-Temperature(TL) -Total Time above TL (t L)	217℃ 30-100 seconds
PEAK	-Temperature(TP) -Time(tp)	260℃ 3 second
RAMP-DOWN	Rate	6℃ / second max.
Time from 25℃ to Peak Temperature		8 minutes max.
Composition of solder paste		96.5Sn/3Ag/0.5Cu
Solder Paste Model		SHENMAO PF606-P26

Note：All the temperature measure point is on top surface of the component, if temperature over recommend, it will make component surface peeling or damage.

The graphic shows temperature profile for component assembly process in reflow ovens



Soldering With Iron:

Soldering condition : Soldering iron temperature 270±10 ℃.

Apply preheating at 120℃ for 2-3 minutes. Finish soldering for each terminal within 3 seconds, if soldering iron over temperature 270±10 ℃ or 3 seconds, it will make component surface peeling or damage.

Soldering iron can not leakage of electricity.